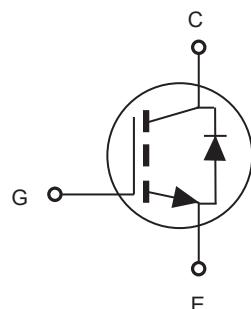
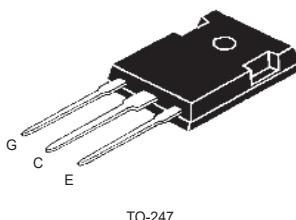


**650V 50A Insulated Gate Bipolar Transistors****FEATURES**

- $V_{CES} = 650V$ ,  $I_C = 50A$  ( $T_c=100^\circ C$ ) .
- Trench Gate and Field Stop Processes IGBT .
- Low  $V_{CE(sat)}$  and High Switching Speed .
- Positive  $V_{CE(sat)}$  Temperature Coefficient .
- 10us of Short-circuit Withstand Time .
- Soft and Fast Recover Antiparallel Diode .

**APPLICATIONS**

- Uninterruptible Power Supplies .
- Solar Converters, Welding Machine.
- Motor Drives .

**ABSOLUTE MAXIMUM VALUES**  $T_c = 25^\circ C$  unless otherwise noted

Parameter	Symbol	Limit	Units
Collector-to-Emitter Breakdown Voltage	$V_{CES}$	650	V
Gate-to-Emitter Voltage	$V_{GE}$	$\pm 30$	V
Continuous Collector Current @ $T_c = 25^\circ C$ @ $T_c = 100^\circ C$	$I_C$	100	A
		50	A
Pulsed Collector Current , tp limited by $T_{jmax}$	$I_{CM}$	150	A
Diode Continuous Forward Current @ $T_c = 25^\circ C$ @ $T_c = 100^\circ C$	$I_F$	100	A
		50	A
Diode Maximum Forward Current	$I_{FM}$	150	A
Power Dissipation@ $T_c=25^\circ C$ @ $T_c=100^\circ C$	$P_D$	278	W
		111	W
Operating Junction Temperature	$T_J$	-55 to 150	$^\circ C$
Storage Temperature Range	$T_{STG}$	-55 to 150	$^\circ C$
Maximum Temperature for Soldering	$T_L$	260	$^\circ C$

**Thermal Characteristics**

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case for IGBT	$R_{JC}$	0.45	$^\circ C/W$
Thermal Resistance, Junction-to-Ambient	$R_{JA}$	40	$^\circ C/W$



# CEWG50N65B

## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

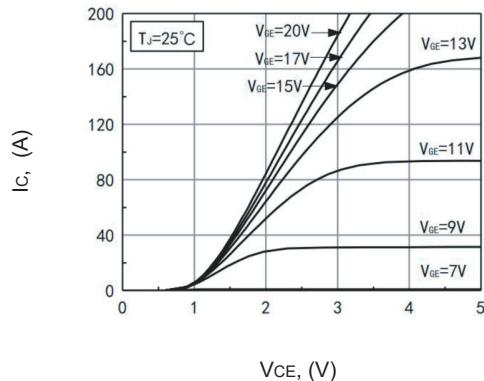
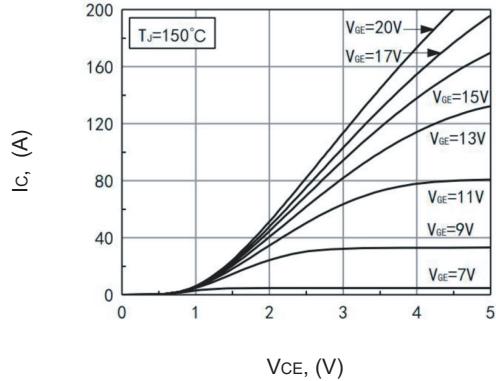
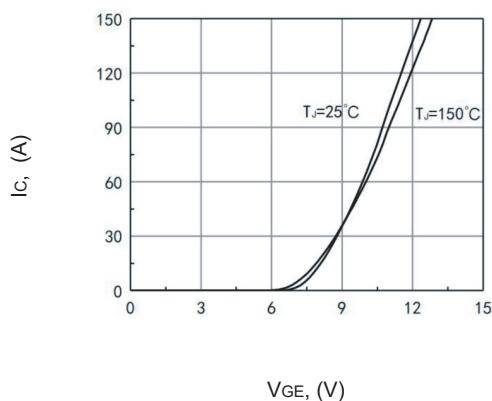
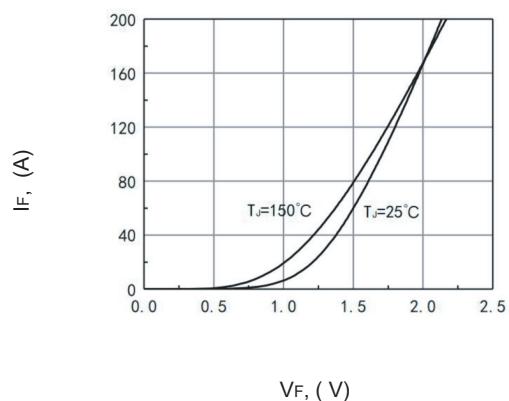
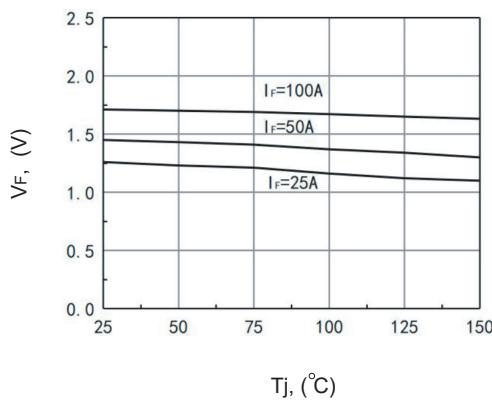
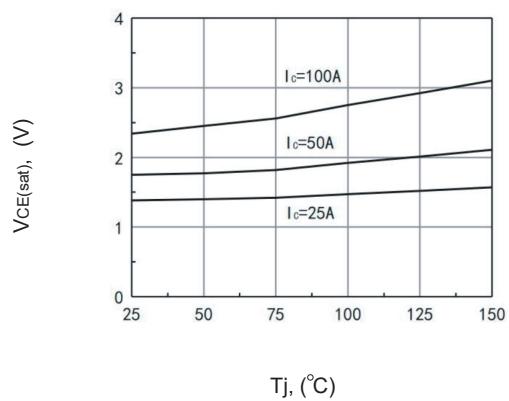
Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Collector-Emitter Breakdown Voltage	$\text{BV}_{\text{CES}}$	$V_{\text{GE}} = 0\text{V}, I_C = 1\text{mA}$	650			V
Zero Gate Voltage Collector Current	$I_{\text{CES}}$	$V_{\text{CE}} = 650\text{V}, V_{\text{GE}} = 0\text{V}$			1	uA
Gate Body Leakage Current, Forward	$I_{\text{GESF}}$	$V_{\text{GE}} = 30\text{V}, V_{\text{CE}} = 0\text{V}$			200	nA
Gate Body Leakage Current, Reverse	$I_{\text{GESR}}$	$V_{\text{GE}} = -30\text{V}, V_{\text{CE}} = 0\text{V}$			-200	nA
Gate Threshold Voltage	$V_{\text{GE}(\text{th})}$	$V_{\text{GE}} = V_{\text{CE}}, I_C = 1\text{mA}$	4.5		6.5	V
Collector-Emitter saturation Voltage	$V_{\text{CE}(\text{sat})}$	$V_{\text{GE}} = 15\text{V}, I_C = 50\text{A}$		1.75	2.35	V
Input Capacitance	$C_{\text{ies}}$	$V_{\text{CE}} = 25\text{V}, V_{\text{GE}} = 0\text{V}, f = 1\text{MHz}$		5030		pF
Output Capacitance	$C_{\text{oes}}$			175		pF
Reverse Transfer Capacitance	$C_{\text{res}}$			80		pF
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{CC}} = 400\text{V}, I_C = 50\text{A}, V_{\text{GE}} = 15\text{V}, R_{\text{GEN}} = 5\Omega$ Inductive Load $T_C = 25^\circ\text{C}$		70		ns
Turn-On Rise Time	$t_r$			82		ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			220		ns
Turn-Off Fall Time	$t_f$			43		ns
Turn-On Switching Loss	$E_{\text{on}}$			2		mJ
Turn-Off Switching Loss	$E_{\text{off}}$			1.1		mJ
Total Switching Loss	$E_{\text{ts}}$			3.1		mJ
Total Gate Charge	$Q_g$	$V_{\text{CC}} = 480\text{V}, I_C = 50\text{A}, V_{\text{GE}} = 15\text{V}$		175		nC
Gate-Emitter Charge	$Q_{\text{ge}}$			42		nC
Gate-Collector Charge	$Q_{\text{gc}}$			77		nC

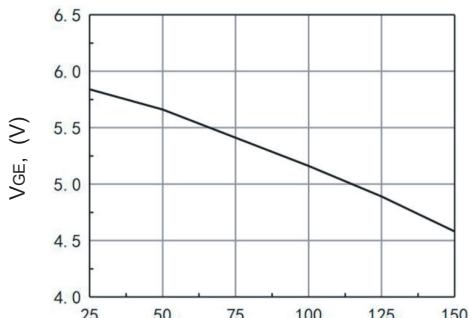
## Electrical Characteristics of Diode $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Diode Forward Voltage	$V_F$	$I_F = 50\text{A}$		1.5	2	V
Diode Reverse Recovery Time	$t_{\text{rr}}$	$I_F = 50\text{A}$ $dI_F / dt = 100\text{A} / \mu\text{s}$		69		ns
Diode peak Reverse Recovery Current	$I_{\text{rr}}$			14		A
Diode Reverse Recovery Charge	$Q_{\text{rr}}$			0.5		uC

Notes :

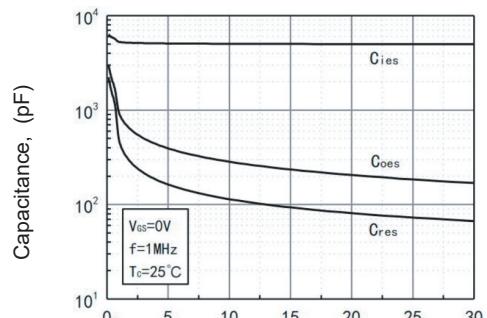
a.Pulse width  $\leq 300\mu\text{s}$ , Duty cycle  $\leq 2\%$ .

**TYPICAL PERFORMANCE CHARACTERISTICS**

**Figure 1. Output Characteristics**

**Figure 2. Output Characteristics**

**Figure 3. Typical Transfer Characteristics**

**Figure 4. Saturation Voltage vs Tc Characteristics**

**Figure 5. Forward Voltage vs Junction Temperature**

**Figure 6. Typical  $V_{CE(\text{sat})}$  vs  $T_j$  Characteristics**



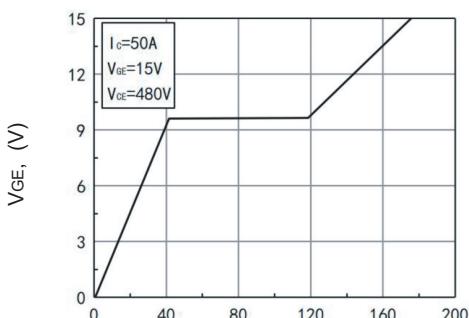
T<sub>J</sub>, (°C)

Figure 7.V<sub>GE(th)</sub> vs T<sub>J</sub> Characteristics



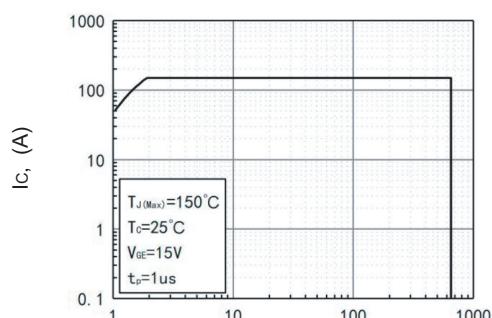
V<sub>CE</sub>, (V)

Figure 8.Capacitance Characteristics



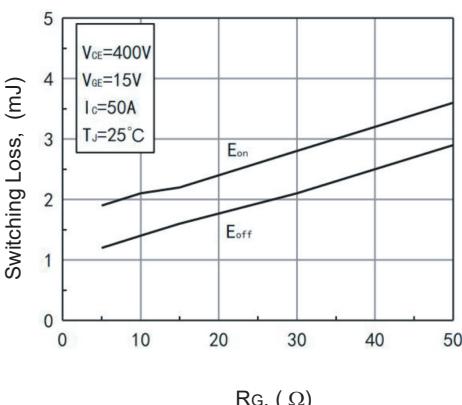
Q<sub>G</sub>, (nC)

Figure 9.Gate Charge Wave Form



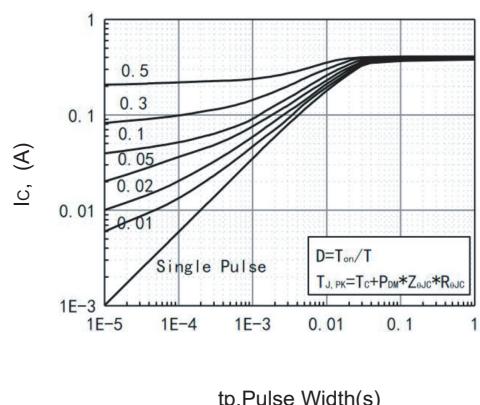
V<sub>CE</sub>, (V)

Figure 10.Forward Bias Safe Operating Area



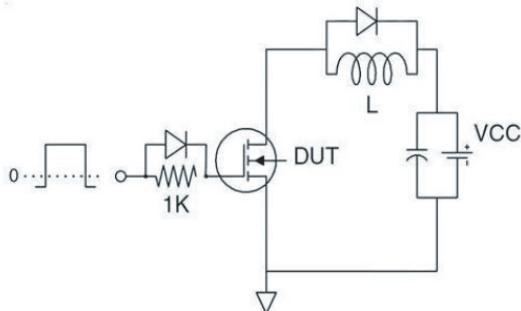
R<sub>G</sub>, (Ω)

Figure 11.Switching Loss vs Gate Resistances

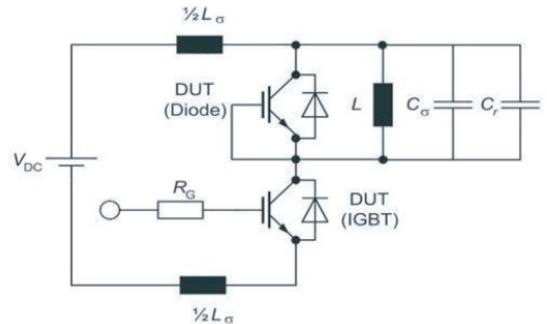


t<sub>p</sub>,Pulse Width(s)

Figure 12.Transient Thermal Resistances

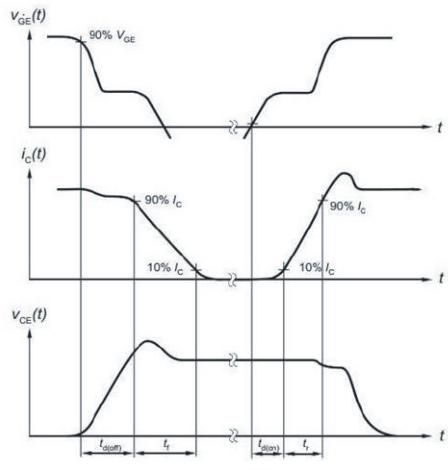


Gate Charge Test Circuit

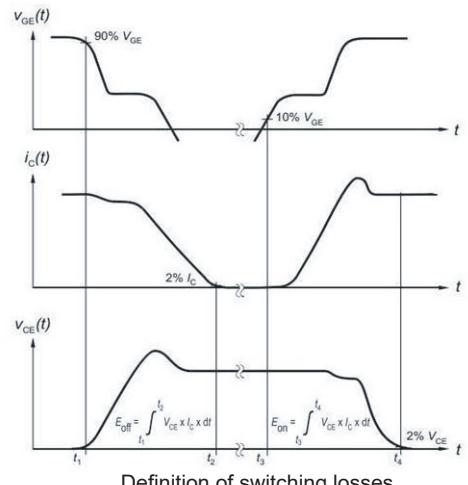


Switch Time Test Circuit

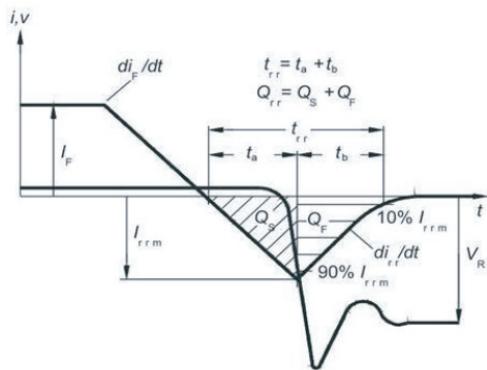
## SWITCHING CHARACTERISTICS



Definition of switching times



Definition of switching losses



Definition of diode switching characteristics